



# FURNACE AND PLASMA TOOLS

**Bruce Technologies 4 Stack Tube Furnace:** High temp processing of Si, SiC and Quartz

tube	wfr	type	process
1	5"	Atm	Clean Dry ox
2	5"	Atm	Dry ox, Wet ox
3	3"	Atm	Wet ox, anneal, Diffusion
4	4"	Vac	Undoped Poly, LTO



**Adixen AMS 100 Deep Reactive Ion Etcher:** High aspect ratio etching of Si & SiO<sub>2</sub> wafers

- Fast thru wafer etching of Silicon (10µm/min in most cases)
- Deep Etching of SiO<sub>2</sub> & Pyrex (>30µm, ~3KA/min)
- No tooling changes to switch from Si to SiO<sub>2</sub> etching
- 4" wafer handling with adapters for smaller wafers or pieces
- Can etch SiC and Diamond with custom recipes



**PlasmaTherm PECVD/RIE PT-700:** Industry standard plasma tool for deposition, etching

- PECVD of Amorphous Silicon, SiO<sub>2</sub>, Silicon nitride
- Standard RIE and Plasma Etch modes available
- RF(13.56MHz) & LF(50KHz) sources for added flexibility
- Large chucks (~11" dia) for big substrates or multiple pieces

